## MSG43004

## SiGe HBT type

#### For low-noise RF amplifier

#### ■ Features

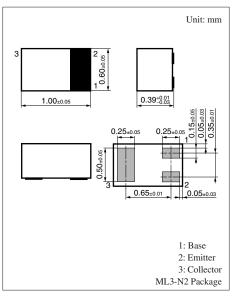
**Transistors** 

- Compatible between high breakdown voltage and high cut-off frequency
- Low noise, high-gain amplification
- Optimal size reduction and high level integration for ultra-small packages

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	9	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	6	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	1	V	
Collector current	$I_C$	100	mA	
Collector power dissipation *	P <sub>C</sub>	100	mW	
Junction temperature	$T_{j}$	125	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	

Note) \*: Copper plate at the collector is  $5.0 \text{ mm}^2$  on substrate at  $10 \text{ mm} \times 12 \text{ mm} \times 0.8 \text{ mm}$ .



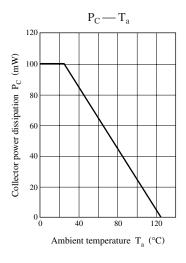
Marking Symbol: 5Y

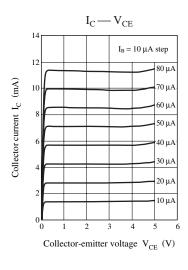
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

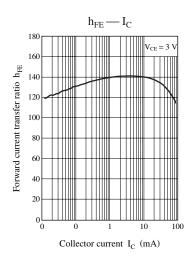
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 9 \text{ V}, I_{E} = 0$			1	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 6 \text{ V}, I_{B} = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 1 \text{ V}, I_{C} = 0$			1	μΑ
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 3 \text{ V}, I_{C} = 15 \text{ mA}$	100		220	_
Transition frequency *	$f_T$	$V_{CE} = 3 \text{ V}, I_{C} = 30 \text{ mA}, f = 2 \text{ GHz}$		17		GHz
Forward transfer gain *	S <sub>21e</sub>   2	$V_{CE} = 3 \text{ V}, I_{C} = 30 \text{ mA}, f = 2 \text{ GHz}$	6.0	9.0		dB
Noise figure *	NF	$V_{CE} = 3 \text{ V}, I_{C} = 15 \text{ mA}, f = 2 \text{ GHz}$		1.4	2.0	dB
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 3 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		0.6	0.9	pF
(Common base, input open circuited) *						

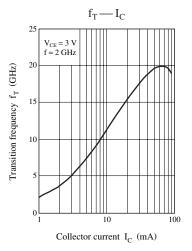
 $Note) \ 1. \ Measuring \ methods \ are \ based \ on \ JAPANESE \ INDUSTRIAL \ STANDARD \ JIS \ C \ 7030 \ measuring \ methods \ for \ transistors.$ 

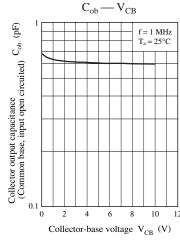
- 2. Observe precautions for handling. Electrostatic sensitive devices.
- 3. \*: Verified by random sampling

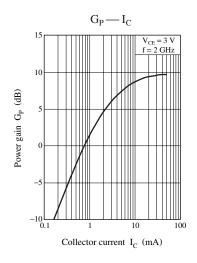


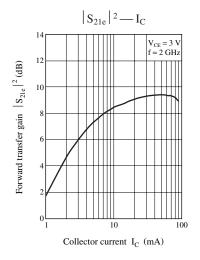


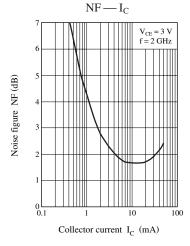


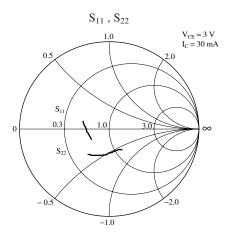


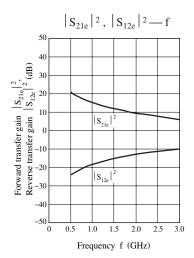












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